



UL 796

STANDARD FOR SAFETY

Printed Wiring Boards

UL Standard for Safety for Printed Wiring Boards, UL 796

Twelfth Edition, Dated October 13, 2020

SUMMARY OF TOPICS:

This revision of ANSI/UL 796 dated August 4, 2021 includes the following changes in requirements:

- ***Update UL/ANSI CEM-3 and FR-4 Types and Editorial Correction; [Table 9.1](#)***
- ***Clarification of Test Pattern Requirements; [Figure 10.1](#), [10.10.1](#), [10.11.1](#), [17.5.4](#) and [17.5.5](#)***
- ***Addition of Reference to 13.1.6 in 13.2 Permanent Coatings Program; [13.2.1](#)***
- ***Addition of Non-Plated via Hole Reference to Notes for [Figure 14.1](#)***
- ***Addition of Reference to Flammability Only PWBs; [16.2.1](#) and [17.8.1](#)***
- ***Clarification of HDI Test Program; [Table 19.1](#)***
- ***Addition of Reference to Ceramic Base Material Exception 9.1.3; [20.1.2](#)***
- ***Addition of Reference to Annex A Sample Construction Examples; [23.2](#)***
- ***Clarification of Optional Use of Release Agent and Clips; [25.2.4](#)***
- ***Clarification of Foil Thickness Measurements by Microsection; [25.4.1](#)***
- ***Clarification of Tolerances on Conditioning Parameters; [27.3.2](#), [28.3](#)(title), [28.3.1](#), [28.3.2](#), [30.2](#), [35.2.4](#) and [35.2.6](#)***
- ***Clarification of HDI Bond Strength, Delamination and Blistering Testing; [34.3.1](#)***
- ***Editorial Updates; [2.4](#), [25.1.2](#), [27.2.3](#), [27.3.2](#) and [27.3.3](#)***

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The new and revised requirements are substantially in accordance with Proposal(s) on this subject dated June 4, 2021.

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Twelfth Edition

October 13, 2020

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The most recent designation of ANSI/UL 796 as an American National Standard (ANSI) occurred on August 4, 2021. ANSI approval for a standard does not include the Cover Page, Transmittal Pages, and Title Page. Any other portions of this ANSI/UL standard that were not processed in accordance with ANSI/UL requirements are noted at the beginning of the impacted sections.

The Department of Defense (DoD) has adopted UL 796 on January 20, 1995. The publication of revised pages or a new edition of this Standard will not invalidate the DoD adoption.

Comments or proposals for revisions on any part of the Standard may be submitted to UL at any time. Proposals should be submitted via a Proposal Request in UL's On-Line Collaborative Standards Development System (CSDS) at <https://csds.ul.com>.

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ANNEX A (Informative) – CONSTRUCTION CONFIGURATIONS

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